

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT5440193

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YONGJIAN HUANG	02/26/2019
TONGBAO DING	02/26/2019
SHENG LI	02/26/2019
P.K. SENTHIL KUMAR	02/25/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TYCO ELECTRONICS (SHANGHAI) CO. LTD.
<b>Street Address:</b>	SECTIONS F, G, H, LEVEL 1, BUILDING 15
<b>Internal Address:</b>	NO. 999 YINGLUN ROAD, CHINA (SHANGHAI) PILOT FREE TRADE ZONE
<b>City:</b>	SHANGHAI
<b>State/Country:</b>	CHINA
<b>Name:</b>	TE CONNECTIVITY INDIA PRIVATE LIMITED
<b>Street Address:</b>	TE PARK SITE #22B
<b>Internal Address:</b>	DODDENAKUNDI INDUSTRIAL AREA, KARNATAKA
<b>City:</b>	BANGALORE
<b>State/Country:</b>	INDIA
<b>Postal Code:</b>	560 048
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16364369
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(610)889-3696
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	610-889-3699
<b>Email:</b>	berwynipdocket@barley.com
<b>Correspondent Name:</b>	BARLEY SNYDER
<b>Address Line 1:</b>	2 GREAT VALLEY PARKWAY
<b>Address Line 2:</b>	SUITE 110
<b>Address Line 4:</b>	MALVERN, PENNSYLVANIA 19355

<b>ATTORNEY DOCKET NUMBER:</b>	21334-2787
<b>NAME OF SUBMITTER:</b>	SALVATORE ANASTASI
<b>SIGNATURE:</b>	/Salvatore Anastasi/
<b>DATE SIGNED:</b>	03/26/2019
<b>Total Attachments: 1</b> source=Declaration#page1.tif	

COMBINED DECLARATION AND ASSIGNMENT

As a below-named inventor, I hereby declare that:

this declaration is directed to inventions and improvements disclosed in:

- the attached application, or
- United States application or PCT International application number \_\_\_\_\_ filed on \_\_\_\_\_, entitled Conductive Terminal and Connector ("the APPLICATION")

The APPLICATION was made or authorized to be made by me;

I believe that I am the original inventor or an original joint inventor of a claimed invention in the APPLICATION;

I have reviewed and understand the contents of the APPLICATION, including the claims, and I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37.C.F.R. 1.56; AND

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

As a below named and signing inventor, acknowledging that I have assigned or have obligations to assign the APPLICATION to:

Tyco Electronics (Shanghai) Co. Ltd. and TE Connectivity India Private Limited ("ASSIGNEE"), corporations organized and existing under and by virtue of the laws of China and India having their principal place of business at Sections F, G and H, Level 1, Building 15, No. 999 Yinglun Road, China (Shanghai) Pilot Free Trade Zone, Shanghai, China and TE Park, 22B, Doddenakundi, 2<sup>nd</sup> Phase, Ind Area, Bangalore 560 048, India and

for a valuable consideration, the receipt of which is hereby acknowledged, I do hereby sell, assign, transfer and set over unto the said ASSIGNEE, its successors and assigns, my full and entire right, title and interest in and to the APPLICATION, the inventions and improvements disclosed in the APPLICATION, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent to be granted and issued therefor, not only for, to and in the rights under the International Convention, and all reissues, re-examinations, renewals or extensions thereof, and I hereby authorize and request the United States Patent and Trademark Office and/or other patent office(s) to issue said Letters Patent to said ASSIGNEE, its successors and assigns, in accordance with this assignment

Legal Name	Signature	Date
HUANG, Yongjian	<i>Justin Huang</i>	2/26/2019
DING, Tongbao	<i>Tongbao Ding</i>	2/26/2019
LI, Shaog	<i>Shaog Li</i>	2/26/2019
KUMAR, P.K. Senthil	<i>P.K. Senthil</i>	2/25/2019